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January 2015

FDMS7692

N-Channel PowerTrench[®] MOSFET 30 V, 7.5 m Ω

Features

- Max $r_{DS(on)} = 7.5 \text{ m}\Omega$ at $V_{GS} = 10 \text{ V}$, $I_D = 13 \text{ A}$
- Max $r_{DS(on)} = 13 \text{ m}\Omega$ at $V_{GS} = 4.5 \text{ V}$, $I_D = 10 \text{ A}$
- Advanced Package and Silicon combination for low r_{DS(on)} and high efficiency
- Next generation enhanced body diode technology, engineered for soft recovery.
- MSL1 robust package design
- 100% UIL tested
- RoHS Compliant

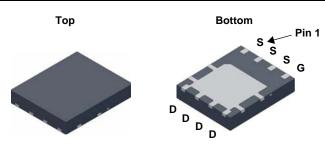


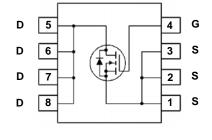
General Description

This N-Channel MOSFET has been designed specifically to improve the overall efficiency and to minimize switch node ringing of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low $r_{DS(on)}$, fast switching speed and body diode reverse recovery performance.

Applications

- IMVP Vcore Switching for Notebook
- VRM Vcore Switching for Desktop and Server
- OringFET / Load Switch
- DC-DC Conversion





Power 56

MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Parameter			Ratings	Units	
V_{DS}	Drain to Source Voltage			30	V	
V _{DSt}	Drain to Source Transient Voltage (tTransient	< 100 ns)		33	V	
V_{GS}	Gate to Source Voltage			±20	V	
	Drain Current -Continuous (Package limited)	T _C = 25 °C		28		
	-Continuous (Silicon limited)	T _C = 25 °C		47	^	
'D	-Continuous	T _A = 25 °C	(Note 1a)	14	_ A	
	-Pulsed			50		
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	21	mJ	
P _D	Power Dissipation	T _C = 25 °C		27	W	
	Power Dissipation	T _A = 25 °C	(Note 1a)	2.5	VV	
T _J , T _{STG}	Operating and Storage Junction Temperature R	ange		-55 to +150	°C	

Thermal Characteristics

I	$R_{ heta JC}$	Thermal Resistance, Junction to Case	4.6	°C/W
I	$R_{ hetaJA}$	Thermal Resistance, Junction to Ambient (Note 1a)	50	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS7692	FDMS7692	Power 56	13 "	12 mm	3000 units

Electrical Characteristics $T_J = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	cteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		13		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 24 V, V _{GS} = 0 V			1	μΑ
I _{GSS}	Gate to Source Leakage Current, Forward	V _{GS} = 20 V, V _{DS} = 0 V			100	nA

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	1.2	2.0	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		-6		mV/°C
		V _{GS} = 10 V, I _D = 13 A		6.5	7.5	
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$		9.5	13	mΩ
, ,		$V_{GS} = 10 \text{ V}, I_D = 13 \text{ A}, T_J = 125 \text{ °C}$		9.0	11	
9 _{FS}	Forward Transconductance	V _{DS} = 5 V, I _D = 13 A		68		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 45 V V 0 V	1015	1350	pF
C _{oss}	Output Capacitance	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz	325	435	pF
C _{rss}	Reverse Transfer Capacitance	1 = 1 101112	45	65	pF
R_g	Gate Resistance		1.0	2.0	Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time		8	16	ns
t _r	Rise Time	V _{DD} = 15 V, I _D = 13 A,	2.7	10	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$	17	31	ns
t _f	Fall Time		2.3	10	ns
Q_g	Total Gate Charge	V _{GS} = 0 V to 10 V	15	22	nC
Q_g	Total Gate Charge	$V_{GS} = 0 \text{ V to } 4.5 \text{ V}$ $V_{DD} = 15 \text{ V}$	7	10	nC
Q_{gs}	Gate to Source Charge	I _D = 13 A	3.4		nC
Q_{gd}	Gate to Drain "Miller" Charge		1.9		nC

Drain-Source Diode Characteristics

V _{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 2.1 \text{ A}$ (Note 2)	0.75	1.1	V
		$V_{GS} = 0 \text{ V}, I_S = 13 \text{ A}$ (Note 2)	0.84	1.2	, v
t _{rr}	Reverse Recovery Time	1 12 A di/dt 100 A/	21	34	ns
Q _{rr}	Reverse Recovery Charge	$I_F = 13 \text{ A, di/dt} = 100 \text{ A/}\mu\text{s}$	6	12	nC
t _{rr}	Reverse Recovery Time	1 12 A di/dt 200 A/vo	17	31	ns
Q _{rr}	Reverse Recovery Charge	$I_F = 13 \text{ A}, \text{ di/dt} = 300 \text{ A/}\mu\text{s}$	12	21	nC

^{1.} R_{0,1} is determined with the device mounted on a 1in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0,1} is guaranteed by design while R_{0CA} is determined by the user's board design.



a. 50 °C/W when mounted on a 1 in² pad of 2 oz copper.



b. 125 °C/W when mounted on a minimum pad of 2 oz copper.

^{2.} Pulse Test: Pulse Width < 300 $\mu s,$ Duty cycle < 2.0%. 3. Starting T $_J$ = 25 °C, L = 0.3 mH, I $_{AS}$ = 12 A, V $_{DD}$ = 27 V, V $_{GS}$ = 10 V.

Typical Characteristics T_J = 25 °C unless otherwise noted

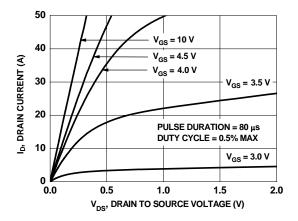


Figure 1. On Region Characteristics

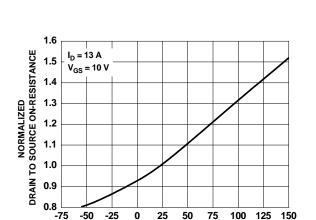


Figure 3. Normalized On Resistance vs Junction Temperature

T_J, JUNCTION TEMPERATURE (°C)

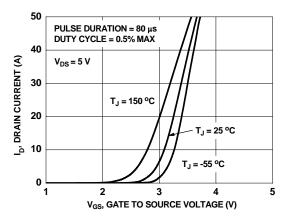


Figure 5. Transfer Characteristics

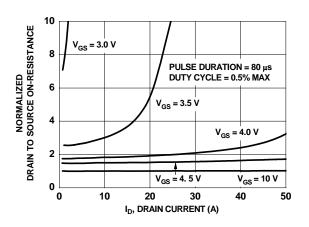


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

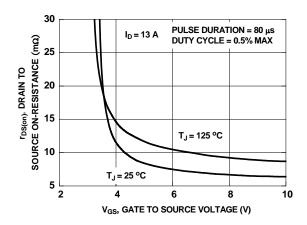


Figure 4. On-Resistance vs Gate to Source Voltage

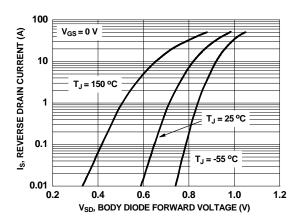


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25$ °C unless otherwise noted

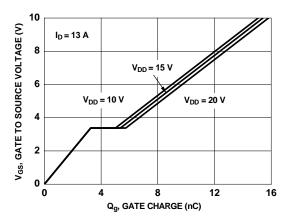


Figure 7. Gate Charge Characteristics

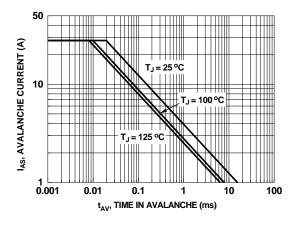


Figure 9. Unclamped Inductive Switching Capability

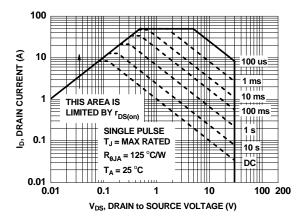


Figure 11. Forward Bias Safe Operating Area

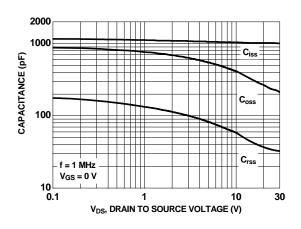


Figure 8. Capacitance vs Drain to Source Voltage

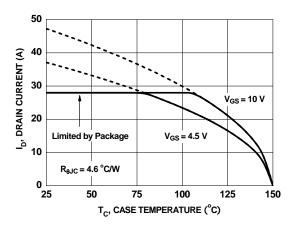


Figure 10. Maximum Continuous Drain Current vs Case Temperature

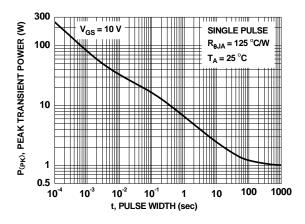


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics $T_J = 25$ °C unless otherwise noted

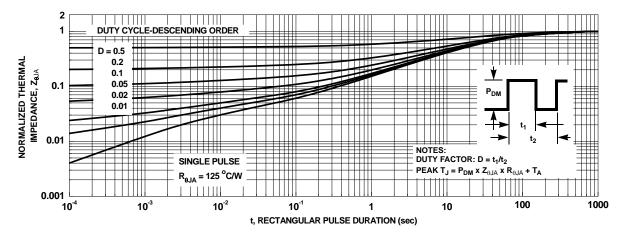


Figure 13. Junction-to-Ambient Transient Thermal Response Curve

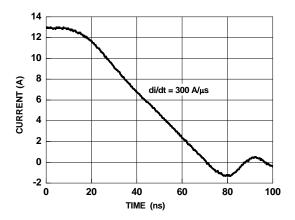
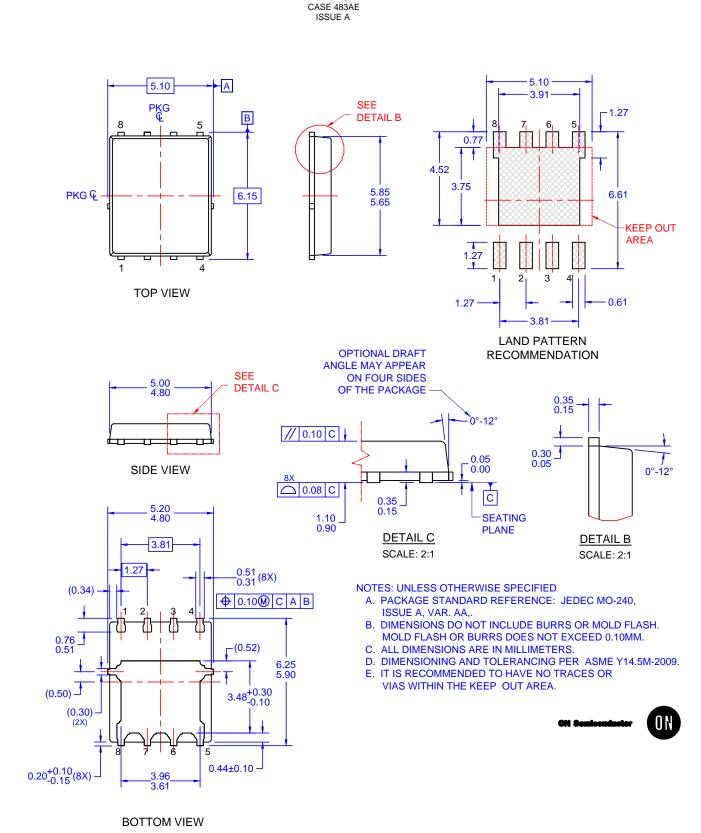


Figure 14. Body Diode Reverse Recovery Characteristics



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